

September 1983 Revised February 1999

MM74HC393 Dual 4-Bit Binary Counter

General Description

The MM74HC393 counter circuits contain independent ripple carry counters and utilize advanced silicon-gate CMOS technology. The MM74HC393 contains two 4-bit ripple carry binary counters, which can be cascaded to create a single divide-by-256 counter.

Each of the two 4-bit counters is incremented on the HIGH-to-LOW transition (negative edge) of the clock input, and each has an independent clear input. When clear is set HIGH all four bits of each counter are set to a low level. This enables count truncation and allows the implementation of divide-by-N counter configurations.

Each of the counters outputs can drive 10 low power Schottky TTL equivalent loads. This counter is functionally

as well as pin equivalent to the 74LS393. All inputs are protected from damage due to static discharge by diodes to V_{CC} and ground.

Features

- Typical operating frequency: 50 MHz
- Typical propagation delay: 13 ns (Ck to Q_A)
- Wide operating supply voltage range: 2-6V
- Low input current: <1 µA
- Low quiescent supply current: 80 µA maximum (74HC Series)
- Fanout of 10 LS-TTL loads

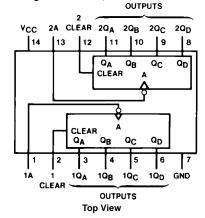
Ordering Code:

Order Number Package Number			Package Description			
	MM74HC393M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow			
	MM74HC393SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
	MM74HC393MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			
	MM74HC393N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide			

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

Pin Assignments for DIP, SOIC, SOP and TSSOP



Absolute Maximum Ratings Recommended Operating (Note 2) **Conditions**

(Note 1)	
Supply Voltage (V _{CC})	-0.5 to +7.0V
DC Input Voltage (V _{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V _{OUT})	-0.5 to V_{CC} $+0.5V$
Clamp Diode Current (I _{IK} , I _{OK})	±20 mA
DC Output Current, per pin (I _{OUT})	±25 mA
DC V _{CC} or GND Current, per pin (I _{CC})	±50 mA
O(T (D (T)	0500 / 45000

Storage Temperature Range (T_{STG}) -65°C to +150°C Power Dissipation (P_D) (Note 3) 600 mW S.O. Package only 500 mW

Lead Temperature (T_L)

(Soldering 10 seconds) 260°C

Max Units Supply Voltage (V_{CC}) 2 6 V DC Input or Output Voltage $(V_{\mathsf{IN}},\,V_{\mathsf{OUT}})$ 0 V_CC V Operating Temperature Range (T_A) °C +85 Input Rise or Fall Times $(t_r, t_f) V_{CC} = 2.0V$ 1000 ns $V_{CC} = 4.5V$ 500 ns $V_{CC} = 6.0V$ 400

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

ns

Note 2: Unless otherwise specified all voltages are referenced to ground. Note 3: Power Dissipation temperature derating — plastic "N" package: 12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		T _A = -40 to 85°C	T _A = -55 to 125°C	Units	
Symbol				Тур		Guaranteed L	imits	Ullits	
V _{IH}	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V	
	Input Voltage		4.5V		3.15	3.15	3.15	V	
			6.0V		4.2	4.2	4.2	V	
V _{IL}	Maximum LOW Level		2.0V		0.5	0.5	0.5	V	
	Input Voltage		4.5V		1.35	1.35	1.35	V	
			6.0V		1.8	1.8	1.8	V	
V _{OH}	Minimum HIGH Level	V _{IN} = V _{IH} or V _{IL}							
	Output Voltage	$ I_{OUT} \le 20 \mu A$	2.0V	2.0	1.9	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	4.4	V	
			6.0V	6.0	5.9	5.9	5.9	V	
		$V_{IN} = V_{IH}$ or V_{IL}							
		$ I_{OUT} \le 4.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V	
		$ I_{OUT} \le 5.2 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V	
V _{OL}	Maximum LOW Level	V _{IN} = V _{IH} or V _{IL}							
	Output Voltage	$ I_{OUT} \le 20 \mu A$	2.0V	0	0.1	0.1	0.1	V	
			4.5V	0	0.1	0.1	0.1	V	
			6.0V	0	0.1	0.1	0.1	V	
		$V_{IN} = V_{IH}$ or V_{IL}							
		$ I_{OUT} \le 4.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V	
		I _{OUT} ≤ 5.2 mA	6.0V	0.2	0.26	0.33	0.4	V	
I _{IN}	Maximum Input	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μА	
	Current								
I _{CC}	Maximum Quiescent	V _{IN} = V _{CC} or GND	6.0V		8.0	80	160	μΑ	
	Supply Current	$I_{OUT} = 0 \mu A$							

Note 4: For a power supply of 5V $\pm 10\%$ the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

 $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

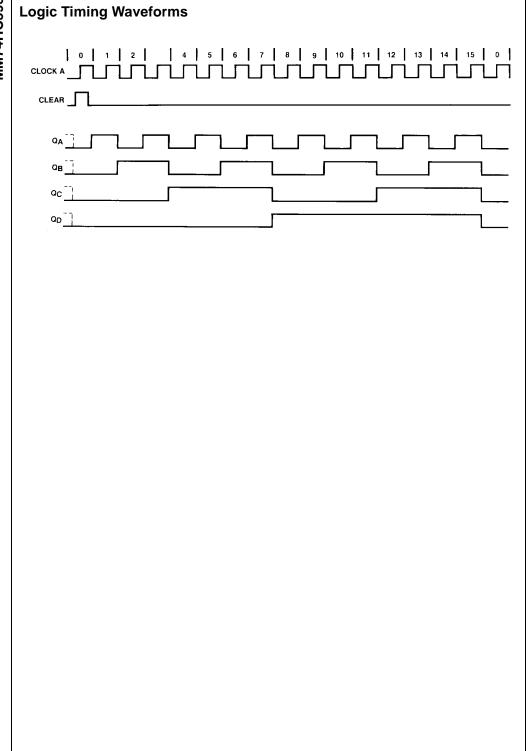
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
f _{MAX}	Maximum Operating Frequency		50	30	MHz
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Clock A to QA		13	20	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Clock A to Q _B		19	35	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Clock A to Q _C		23	42	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Clock A to Q _D		27	50	ns
t _{PHL}	Maximum Propagation Delay, Clear to any Q		15	28	ns
t _{REM}	Minimum Removal Time		-2	5	ns
t _W	Minimum Pulse Width Clear or Clock		10	16	ns

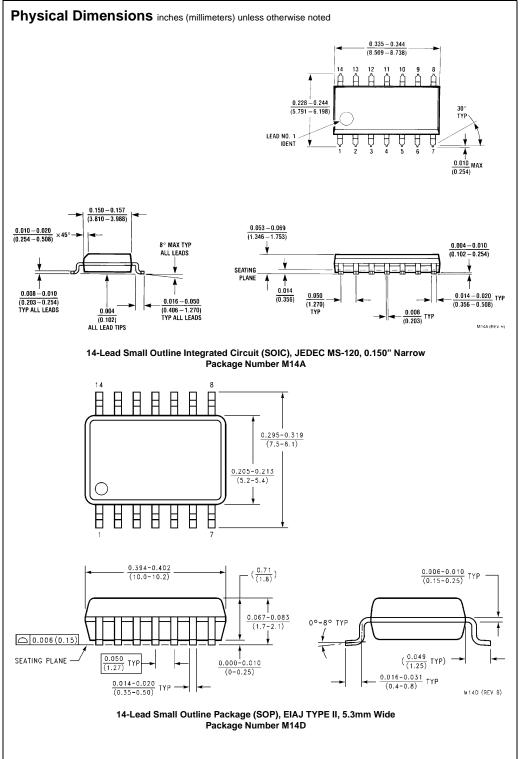
AC Electrical Characteristics

 $C_L = 50 \text{ pF}, t_f = t_f = 6 \text{ ns} \text{ (unless otherwise specified)}$

Combal	Parameter	Conditions		T _A = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$ $T_A = -55 \text{ to } 125^{\circ}\text{C}$		Units
Symbol			V _{CC}	Тур	Guaranteed Limits			
f _{MAX}	Maximum Operating		2.0V		5	4	3	
	Frequency	1	4.5V	1	27	21	18	MHz
		1	6.0V		31	24	20	MHz
t _{PHL} , t _{PLH}	Maximum Propagation		2.0V	45	120	150	180	ns
	Delay Clock A to Q _A	1	4.5V	15	24	30	35	ns
		1	6.0V	13	21	26	31	ns
t _{PHL} , t _{PLH}	Maximum Propagation		2.0V	68	190	240	285	ns
	Delay Clock A to Q _B	1	4.5V	23	38	47	57	ns
		1	6.0V	20	32	40	48	ns
t _{PHL} , t _{PLH}	Maximum Propagation		2.0V	90	240	300	360	ns
	Delay Clock A to Q _C	1	4.5V	30	48	60	72	ns
		1	6.0V	26	41	51	61	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay		2.0V	100	290	360	430	ns
	Clock to Q _D	1	4.5V	35	58	72	87	ns
		1	6.0V	30	50	62	75	ns
t _{PHL}	Maximum Propagation		2.0V	54	165	210	250	ns
	Delay Clear to any Q	1	4.5V	18	33	41	49	ns
		1	6.0V	15	28	35	42	ns
t _{REM}	Minimum Clear	[2.0V		25	25	25	ns
	Removal Time	1	4.5V	1	5	5	5	ns
		1	6.0V	1	5	5	5	ns
t _W	Minimum Pulse Width		2.0V	30	80	100	120	ns
	Clear or Clock	1	4.5V	10	16	20	24	ns
		1	6.0V	9	14	18	20	ns
t_{THL}, t_{TLH}	Maximum Output		2.0V	30	75	95	110	ns
	Rise and Fall Time	1	4.5V	8	15	19	22	ns
		1	6.0V	7	13	16	19	ns
t _r , t _f	Maximum Input		+		1000	1000	1000	ns
	Rise and Fall Time	1			500	500	500	ns
		1		1	400	400	400	ns
C _{PD}	Power Dissipation	(per counter)	1	42				pF
	Capacitance (Note 5)	1						
C _{IN}	Maximum Input Capacitance		1	5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC}^1 + I_{CC}$.

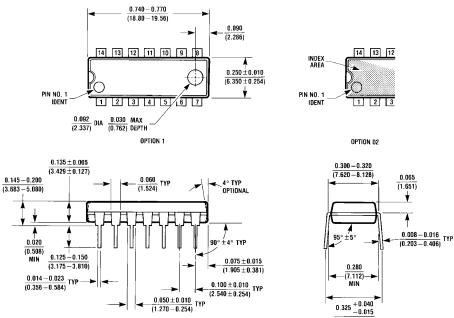




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Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE 5.0±0.1 -A-0.43 TYP 7.72 4.16 6.4 -B-3.2 LAND PATTERN RECOMMENDATION PIN #1 IDENT. SEE DETAIL A ALL LEAD TIPS -0.90^{+0.15} -C-0.10±0.05 0.65 -12.00°TOP & BOTTO R0.16 R0.31-GAGE PLANE NOTES 0.25 A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB-REF NOTE 6, DATED 7/93 0°-8° B. DIMENSIONS ARE IN MILLIMETERS SEATING PLANE C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS 0.6±0.1 -1.00-DETAIL A 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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